

MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3			
Semiconductor Device Type: MF (A6X) 008 DFN-S 6x5 mm Matte Tin												
Basic Substance		CAS Number	"Contained In" Sub-Component		% Total Weight	mg/part	ppm	37.77	(mg) Total	Mold Compound	% of Total Weight	49.12
Silica, fused		60676-86-0	Mold Compound		44.208	33.996	442,080	Epoxy Resin (NLP # 500-033-5)	Silica, fused	60676-86-0	90.00	
Epoxy Resin (NLP # 500-033-5)		Trade Secret	Mold Compound		2.382	1.832	23,823		Trade Secret	4.85		
Phenolic Resin		Trade Secret	Mold Compound		2.382	1.832	23,823		Trade Secret	4.85		
Carbon Black		1333-86-4	Mold Compound		0.147	0.113	1,474		Carbon Black	1333-86-4	0.30	
Copper		7440-50-8	Lead Frame		42.960	33.036	429,600		Total		100.00	
Tin		7440-31-5	Lead Frame		0.110	0.085	1,103	33.91	(mg) Total	Lead Frame	% of Total Weight	44.1
Silver		7440-22-4	Lead Frame		0.840	0.646	8,401		Copper	7440-50-8	97.42	
Zinc		7440-66-6	Lead Frame		0.079	0.061	794		Tin	7440-31-5	0.25	
Chromium		7440-47-3	Lead Frame		0.110	0.085	1,103		Silver	7440-22-4	1.91	
Silver		7440-22-4	Die Attach		0.320	0.246	3,198		Zinc	7440-66-6	0.18	
Acrylate resins Proprietary		Trade Secret	Die Attach		0.074	0.057	738		Chromium	7440-47-3	0.25	
Treated silica		Trade Secret	Die Attach		0.008	0.006	82	Total		100.00		
Heterocyclic organic compound		Trade Secret	Die Attach		0.008	0.006	82	0.32	(mg) Total	Die Attach	% of Total Weight	0.41
Silicon		7440-21-3	Chip (Die)		2.870	2.207	28,700	Acrylate resins Proprietary	Silver	7440-22-4	78	
Gold		7440-57-5	Wire Bond		0.170	0.131	1,700		Trade Secret	18		
Tin		7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour		3.330	2.561	33,300		Treated silica	Trade Secret	2	
									Heterocyclic organic compound	Trade Secret	2	
TOTALS:					100.000	76.900	1,000,000	Total		100.00		
0.0769 g Total Mass												
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)												
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.												
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.												
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/												
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.												
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table												

2.21		Total (mg)	Chip (Die)	% of Total Weight	2.87
		Doped Silicon	7440-21-3	100	
		Total		100.00	
0.13		(mg) Total	Wire Bond	% of Total Weight	0.17
		Doped Gold	7440-57-5	100	
		Total		100.00	
2.56		(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	3.33
		Tin	7440-31-5	100.00	
		Total		100.00	
76.900		100.000			